Single Wafer Process Excellence

Defectivity Improvement

Velocity

Target Applications

- Particle removal (scrubber)
- Sensitive structure particle removal
- Pre-lithography
- 3D packaging

Key Benefits

- Defect removal from sensitive structures without etching/damage
- Residue and particle removal in a single process
- Removal of < 35nm particles
- Frontside, backside and edge defect removal
- Enhanced rinsing with physical energy
- Watermark-free drying
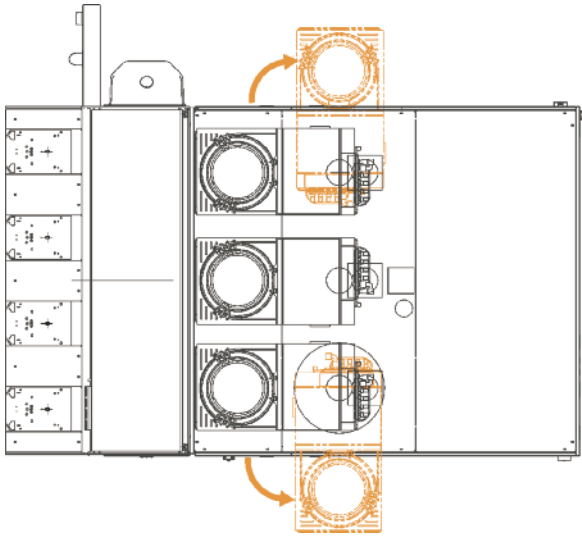- Cost effective, reliable platform

Design Features

- Stacked chambers provide reduced footprint and reduced robotics
- Independent frontside and backside process control
- Chemical module for dilute RCA solutions and semi-aqueous solvents, either single pass or reclaimed.
- Complete 300mm factory automation capability
- FOUP, SMIF and open cassette (MOCA) loadport options
- Comprehensive service design, including slide-out chambers
- Safety certification - S2/S8, CE, FM7-7

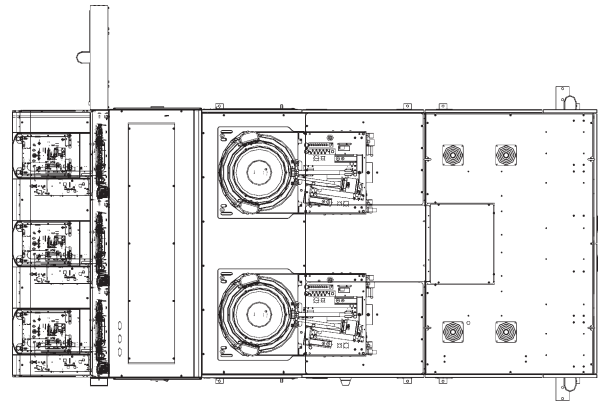|	Velocity[6]	Velocity[4]
Load Ports:	4	3
Chambers:	6	4
Throughput (WPH):	275 for 60s process	185 for 60s process
MTBI/MTBF (HOURS): >	250 / >500	250 / > 500

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VELOCITY PLATFORM
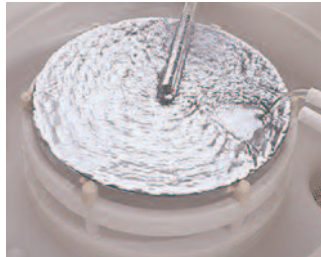
Platform Layout

Velocity⁶ Dimensions
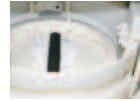2.65m wide x 3.39m deep x 2.41m high

Velocity⁴ Dimensions
2.28m wide x 3.36m deep x 2.41m high

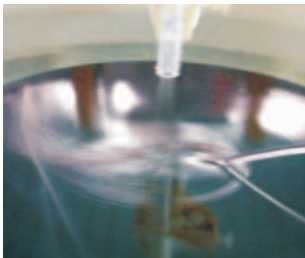## Physical Clean and Dry Technology

Goldfinger® Megasonics
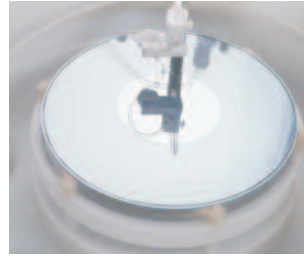remove defects from
sensitive structures

Backside Megasonics
high efficiency
back-side particle removal

JetStream-Nano™
combines with meg clean
for additional cleaning
during DIW rinse

Sahara™
provides watermark-free drying

**Chemical
Direct Dispense**
for very low chemical usage

Single-Wafer and Batch-Immersion Cleaning

NAURA Akrion also has a complete line of batch immersion products for a variety of cleaning, etching and stripping applications. Our batch immersion and single wafer systems are found in leading edge fabs worldwide.

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AKRION**